

A B S T R A C T

APPLYING A LIQUID DOPANT SOLUTION ON A WAFER

Device (1) for applying a liquid dopant solution on a wafer (3), comprising a dopant distribution device (5), a rotatable horizontally translatable dopant-transfer roll (7) between a first roll position (15) and a second roll position, and a work table (9) for holding the wafer (3), wherein the distribution device (5) comprises a dopant-transfer block (20) and a fluid container (24) having an open side enclosed by an edge (26), which open side is directed to the dopant-transfer block (20), wherein the block holder (21) is horizontally translatable between a first block position in which the dopant-transfer block is under the open side of the fluid container and a second block position (31) in which the dopant-transfer block (20) has contacted the rotatable dopant-transfer roll (7) in its first roll position (15), wherein during normal operation in the second roll position the rotatable dopant-transfer roll (7) has contacted the wafer (3) to provide dopant solution onto the surface of the wafer (3).

(Figure 1b)